



Title of Change:	LSI FLIP fab site change from Gunma, Japan to Niigata, Japan													
Proposed first ship date:	12 September 2016													
Contact information:	Contact your local ON Semiconductor Sales Office or Akira.Yoneyama@onsemi.com													
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or Makoto.Nakaoka@onsemi.com													
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>													
Change Part Identification:	Product lots will be identified through a date code marked on the parts													
Change category(s):	<table border="0"> <tr> <td><input type="checkbox"/> Wafer Fab Change</td> <td><input checked="" type="checkbox"/> Manufacturing Site Change/Addition</td> <td><input type="checkbox"/> Product specific change</td> </tr> <tr> <td><input type="checkbox"/> Assembly Change</td> <td><input type="checkbox"/> Manufacturing Process Change</td> <td><input type="checkbox"/> Datasheet/Product Doc change</td> </tr> <tr> <td><input type="checkbox"/> Test Change</td> <td><input type="checkbox"/> Material Change</td> <td><input type="checkbox"/> Shipping/Packaging/Marking</td> </tr> <tr> <td></td> <td></td> <td><input type="checkbox"/> Other: _____</td> </tr> </table>		<input type="checkbox"/> Wafer Fab Change	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition	<input type="checkbox"/> Product specific change	<input type="checkbox"/> Assembly Change	<input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Datasheet/Product Doc change	<input type="checkbox"/> Test Change	<input type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking			<input type="checkbox"/> Other: _____
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Sites Affected:	<table border="0"> <tr> <td><input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable</td> <td><u>Site 1</u> ON Niigata, Japan</td> <td><u>Site 2</u></td> </tr> <tr> <td><input checked="" type="checkbox"/> ON Semiconductor site(s) :</td> <td></td> <td></td> </tr> <tr> <td><input type="checkbox"/> External Foundry/Subcon site(s):</td> <td></td> <td></td> </tr> </table>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable	<u>Site 1</u> ON Niigata, Japan	<u>Site 2</u>	<input checked="" type="checkbox"/> ON Semiconductor site(s) :			<input type="checkbox"/> External Foundry/Subcon site(s):						
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Description and Purpose:	<p>To be able to continuously supply products and increase our supply capacity to support increased demand, LSI FLIP site will be changed from Gunma, Japan to Niigata, Japan. All equipment and most personnel will be transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified. Neither change in electrical characteristics, nor change in product reliability is expected</p>													



Qualification Plan:

Estimated date for qualification completion: 10 June 2016

IC Reliability Plan

1.0

REFERENCE DOCUMENTS: 12MSB17722C - Product Reliability Qualification Process Specification

2.0

WLP/FLIP Reliability Plan

Fab site change from Gunma, Japan to Niigata, Japan

3.0

Package	WLCSP179 WLCSP36 WLFCP6	Wafer Fab Site	Niigata
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4.0

RELIABILITY TESTING REQUIREMENTS

Test	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
HTOL	TJ ~ 150°C, for 1008 hrs	Test @ Room	77	3	231	
HTSL	150°C for 1008 hrs	Test @ Room	77	3	231	
THB	85°C/85% RH for 1008 hrs	Test @ Room	77	3	231	
TC	-40°C to +125°C for 500 cycles	Test @ Room	77	3	231	

Samples should be available after completion of Qualification.

List of affected Standard Parts:

- LE24162LBXA-SH
- LE24163LBXA-SH
- LE2416RLBXA-SH